

PMP9522 REV B BOM

Designator	Quantity	Value	Description	Package	PartNumber	Manufacturer
C1	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H104K	TDK
C2, C5	2	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H103K	TDK
C4	1	1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	0603	C1608X5R1C105K	TDK
C3	1	330pF	CAP, CERM, 330pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H331J	TDK
D1	1	BAT54C	Diode, Schottky, 30V, 0.2A, SOT-23	SOT-23	BAT54C	Diodes Inc.
D100	1	SMCJ48CA	Diode, Schottky, TVS, bidirectional, 48V, 1500W, SMC	SMC	SMCJ48CA	Bourns
J3	1		Header, 100mil, 2x1, Tin plated, TH	Header, 2 PIN, 100mil, Tin	PEC02SAAN	Sullins
J4	1		Terminal Block, 6A, 3.5mm Pitch, 2-Pos, TH	7.0x8.2x6.5mm	ED555/2DS	OST
Q1, Q2	2	CSD19502Q5B	MOSFET, N-CH, 80V, 3.4 mOhms, SON 5x6mm	SON 5x6mm	CSD19502Q5B	TI
R3	1	1.00k	RES, 1.00k ohm, 1%, 0.1W, 0603	0603	CRCW06031K00FKEA	Vishay-Dale
R4, R5	2	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
R6	1	10.7k	RES, 10.7k ohm, 1%, 0.1W, 0603	0603	CRCW060310K7FKEA	Vishay-Dale
R2	1	3.3	RES, 3.3 ohm, 5%, 0.1W, 0603	0603	CRCW06033R30JNEA	Vishay-Dale
T1	1	PA0173NLT	Transformer, Gate Drive, 980uH, SMT	460x160x340mil	PA0173NLT	Pulse
TP1, TP2, TP5, TP7, TP8	5	Red	Test Point, Multipurpose, Red, TH	Keystone5010	5010	Keystone
TP3, TP4, TP6, TP9	4	Black	Test Point, Multipurpose, Black, TH	Keystone5011	5011	Keystone
U1	1	UCC2808D-2	Low Power Push-Pull PWM with Current Control, 50 % Duty Cycle, -40 to +125 degC, 8-pin SOIC (D), Green (RoHS & no Sb/Br)	D0008A	UCC2808D-2	TI

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